

Listing of Claims

1-23. (Cancelled)

24. (Previously Presented) An assembly for enclosing one or more electronic devices, comprising:

a receptacle having a wall forming a cavity having an opening and a flange surrounding the opening;

a first structural member of the building, wherein the receptacle is attached thereto;

a bracket attached to the receptacle and spanning the opening;

an outer wall layer disposed at least in part over each of the receptacle, bracket, opening, and first structural member.

25. (Previously Presented) The assembly of claim 24, wherein the wall comprises a hole, and wherein the assembly further comprises a wire portion extending through the hole into the cavity.

26. (Previously Presented) The assembly of claim 25, wherein the wire portion forms a coil inside the cavity.

27. (Previously Presented) The assembly of claim 25, wherein the wire portion forms a zigzag inside the cavity.

28. (Previously Presented) The assembly of claim 24, further comprising a vapor barrier disposed between the flange and the outer wall layer.

29. (Previously Presented) The assembly of claim 28, wherein the vapor barrier is sealed to the flange.

30. (Previously Presented) The assembly of claim 29, further comprising an adhesive disposed between the vapor barrier and the flange.

31. (Previously Presented) The assembly of claim 24, wherein the wall comprises a generally flat base.

32. (Previously Presented) The assembly of claim 31, wherein the flat base comprises a raised pattern.

33. (Previously Presented) The assembly of claim 31, wherein the flat base comprises a printed pattern.

34. (Previously Presented) The assembly of claim 24, wherein the wall comprises a pattern of concentric shapes.

35. (Previously Presented) The assembly of claim 34, wherein the pattern of concentric shapes is a pattern of circles.

36. (Previously Presented) A method of enclosing a low-voltage electronic device, comprising the steps of:

providing a receptacle having a wall forming a cavity having an opening and a flange surrounding the opening;

positioning the receptacle within a wall of a building so as to allow the flange to contact a flat surface of a structural member of the building;

securing the flange to the structural member;

securing a bracket across the opening;

installing a wall layer at least in part over each of the receptacle, bracket, opening, and structural member;

forming a hole in the wall layer in communication with the opening of the cavity; and

attaching the low-voltage electronic device to the bracket.

37. (Previously Presented) The method of claim 36, further comprising the steps of:

providing a vapor barrier;
sealing the vapor barrier to the flange of the receptacle; and
forming a hole in the vapor barrier in communication with the opening of the cavity of the receptacle.

38. (Previously Presented) The method of claim 37, further comprising the step of applying an adhesive to the flange.

39. (Previously Presented) The method of claim 36, wherein the wall comprises a generally flat base.

40. (Previously Presented) The method of claim 39, wherein the flat base comprises a raised pattern.

41. (Previously Presented) The method of claim 39, wherein the flat base comprises a pattern of concentric geometric shapes.

42. (Previously Presented) The method of claim 41, wherein the pattern of concentric geometric shapes is a pattern of concentric circles.

43. (Previously Presented) The method of claim 36, further comprising the steps of:

forming a hole in the wall; and
introducing a portion of a wire through the hole into the cavity.

44. (Previously Presented) The method of claim 43, further comprising the step of forming the wire portion into a zigzag pattern.

45. (Previously Presented) The method of claim 43, wherein the wire portion forms a coil.

46. (Previously Presented) The method of claim 43, further comprising the step of sealing the hole with a sealant subsequent to the introduction of the wire portion.